

BS EN 62137-1-4:2009



BSI British Standards

Surface mounting technology — Environmental and endurance test methods for surface mount solder joint —

Part 1-4: Cyclic bending test

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National foreword

This British Standard is the UK implementation of EN 62137-1-4:2009. It is identical to IEC 62137-1-4:2009.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic assembly technology.

A list of organizations represented on this committee can be obtained on request to its secretary.

This publication does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

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English version

**Surface mounting technology -
Environmental and endurance test methods
for surface mount solder joint -
Part 1-4: Cyclic bending test
(IEC 62137-1-4:2009)**

Technologie de montage en surface -
Méthodes d'essais d'environnement
et d'endurance des joints brasés
montés en surface -
Partie 1-4: Essai de flexion cyclique
(CEI 62137-1-4:2009)

Oberflächenmontage-Technik -
Verfahren zur Prüfung
auf Umgebungseinflüsse
und zur Prüfung der Haltbarkeit
von Oberflächen-Lötverbindungen -
Teil 1-4: Zyklische Biegeprüfung
(IEC 62137-1-4:2009)

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: avenue Marnix 17, B - 1000 Brussels

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Foreword

The text of document 91/815/FDIS, future edition 1 of IEC 62137-1-4, prepared by IEC TC 91, Electronics assembly technology, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62137-1-4 on 2009-02-01.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2009-11-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2012-02-01

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 62137-1-4:2009 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-1	- ¹⁾	Environmental testing - Part 1: General and guidance	EN 60068-1	1994 ²⁾
IEC 60194	- ¹⁾	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	2006 ²⁾
IEC 61188-5	Series	Printed boards and printed board assemblies - Design and use - Part 5: Attachment (land/joint) considerations	EN 61188-5	Series
IEC 61190-1-2	- ¹⁾	Attachment materials for electronic assembly - Part 1-2: Requirements for soldering paste for high-quality interconnects in electronics assembly	EN 61190-1-2	2007 ²⁾
IEC 61190-1-3	- ¹⁾	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications	EN 61190-1-3	2007 ²⁾
IEC 61249-2-7	- ¹⁾	Materials for printed boards and other interconnecting structures - Part 2-7: Reinforced base materials, clad and unclad - Epoxide woven E-glass laminated sheet of defined flammability (vertical burning test), copper-clad	EN 61249-2-7 + corr. September	2002 ²⁾ 2005
IEC 61760-1	- ¹⁾	Surface mounting technology - Part 1: Standard method for the specification of surface mounting components (SMDs)	EN 61760-1	2006 ²⁾

¹⁾ Undated reference.

²⁾ Valid edition at date of issue.

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